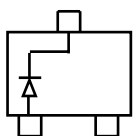
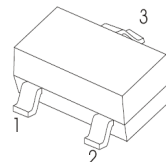
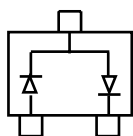


SOT-23 Plastic-Encapsulate Diodes
FEATURES

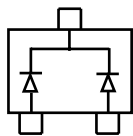
- Low turn-on voltage
- Fast switching
- Also available in lead free version

SOT-23


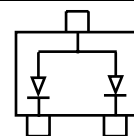
BAS70 Marking: 73



BAS70-04 Marking: 74




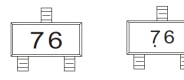


BAS70-05 Marking: 75



BAS70-06 Marking: 76

MARKING:

BAS70	BAS70-04	BAS70-05	BAS70-06
			

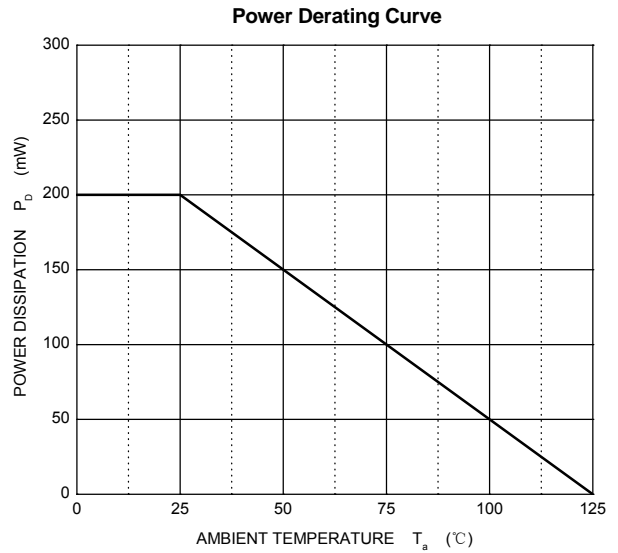
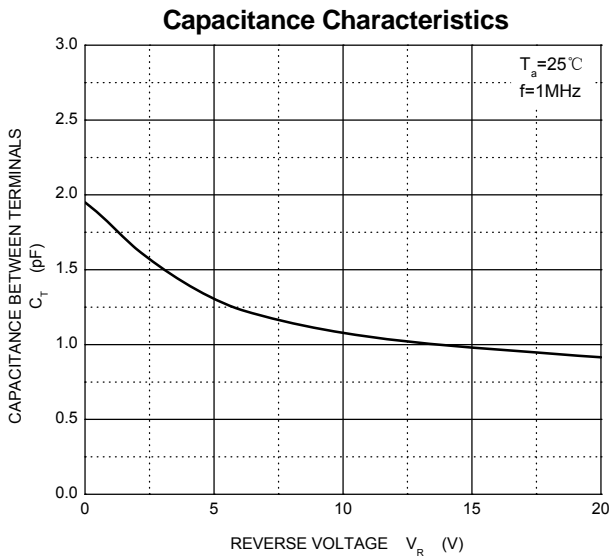
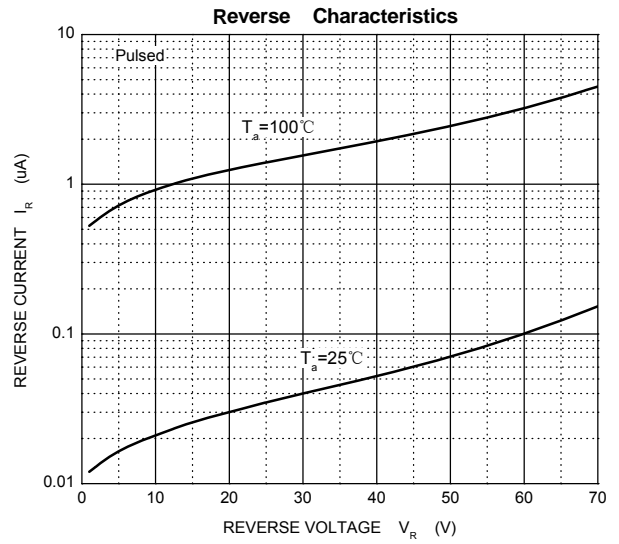
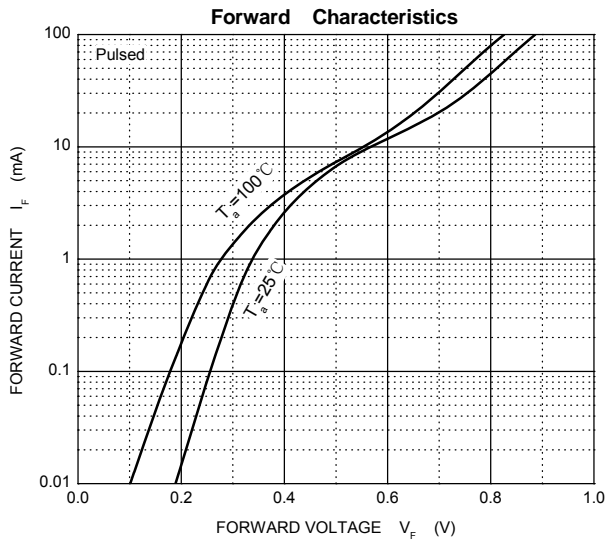
Solid dot = Green molding compound device, if none, the normal device.

MAXIMUM RATINGS @T_a = 25°C

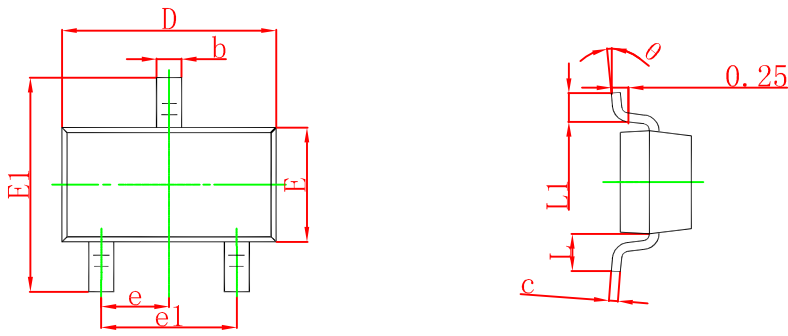
Symbol	Parameter	Value	Unit
V_R	DC Voltage	70	V
I_F	Forward Continuous Current	70	mA
I_{FSM}	Non-Repetitive Peak Forward Surge Current @ t = 8.3ms	100	mA
P_D	Power Dissipation	200	mW
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	500	°C/W
T_J	Junction Temperature	125	°C
T_{stg}	Storage Temperature	-55~+150	°C

ELECTRICAL CHARACTERISTICS (T_a = 25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Max	Unit
Reverse breakdown voltage	$V_{(BR)}$	$I_R = 10\mu A$	70		V
Reverse voltage leakage current	I_R	$V_R = 50V$		100	nA
Forward voltage	V_F	$I_F = 1mA$ $I_F = 15mA$		410 1000	mV
Diode capacitance	C_D	$V_R = 0V$ f = 1MHz		2	pF
Reverse recovery time	t_{rr}	$I_F = I_R = 10mA, I_{rr} = 0.1I_R,$ $R_L = 100\Omega$		5	ns



SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.